ASDCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES	PC. Bannockl	burn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the s encompasse	ubstances es all lowe	within the r level mate	manufacture erials for wh	er listed ite ich the ma	m. Note: nufacture	if the item is an as r has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribut				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplier Information															
Company name* Con			Company unique ID			Unique ID Authority					Response Date*				
nsemi							2024				2024-05-1	24-05-18			
tact Name Title - Contact			ct	I			Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product En			t Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repr			resentative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Env			nviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Iten	n Number	mber Mfr Item Name			Effective Dat	Date Version Manufacturing Site		ing Site	W	eight*	UOM	Unit Type		
	SZ1SMI	35913BT3G	ZEN SMB REG 3W 3.3V SPCL			2024-05-18			VN5		11	4.91	mg	Each	
Manufacturing Proccess Informa	tion							·					·		
Terminal Plating / Grid Array M	terial Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Pro	ak Process Body Temperature		re Max Time at Peak Tempera		Femperatu	e Num	ber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		second	3			
omments															
vel 1 - maximum time at peak temperatu	ire during so	Idering is 10-3	0 seconds												
or more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	16.81	mg	Supplier	Zinc (Zn)	7440-66-6		0.0202	mg
			Supplier	Iron (Fe)	7439-89-6		0.395	mg
			Supplier	Copper (Cu)	7440-50-8		16.3897	mg
			Supplier	Phosphorus (P)	7723-14-0		0.005	mg
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3		0.7	mg
Die Attach Solder	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.013	mg
			А	Lead (Pb)	7439-92-1	7a	0.481	mg
			Supplier	Tin (Sn)	7440-31-5		0.026	mg
Lead Frame	46.99	mg	Supplier	Zinc (Zn)	7440-66-6		0.0564	mg
			Supplier	Iron (Fe)	7439-89-6		1.1043	mg
			Supplier	Copper (Cu)	7440-50-8		45.8153	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0141	mg
Mold Compound-Black	48.07	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.807	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2403	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.9701	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.2455	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.807	mg
Plating	1.82	mg	Supplier	Tin (Sn)	7440-31-5		1.82	mg